# **Quad OR/NOR Gate**

The MC10101 is a quad 2-input OR/NOR gate with one input from each gate common to pin 12.

**LOGIC DIAGRAM** 

- P<sub>D</sub> = 25 mW typ/gate (No Load)
- $t_{pd} = 2.0 \text{ ns typ}$
- $t_r$ ,  $t_f = 2.0$  ns typ (20%–80%)

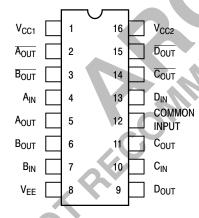
# ON Semiconductor

#### http://onsemi.com

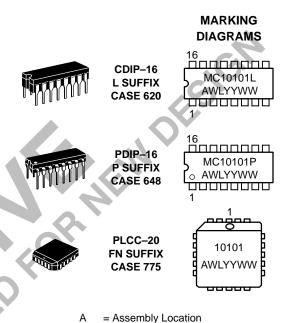
## 2 5 7 3 6 10 14 11 13 12 V<sub>CC1</sub> = PIN 1 V<sub>CC2</sub> = PIN 16

#### DIP PIN ASSIGNMENT

V<sub>EE</sub> = PIN 8



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



## ORDERING INFORMATION

WL = Wafer Lot YY = Year

WW = Work Week

Device	Package	Shipping
MC10101L	CDIP-16	25 Units / Rail
MC10101P	PDIP-16	25 Units / Rail
MC10101FN	PLCC-20	46 Units / Rail

#### **ELECTRICAL CHARACTERISTICS**

Characteristic			Test Limits							
Characteristic		Pin Under	-30	)°C	+25°C			+85°C		
Onaracteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Uni
Power Supply Drain Current	Ι <sub>Ε</sub>	8		29		20	26		29	mAc
Input Current	I <sub>inH</sub>	4 12		425 850			265 535		265 535	μAd
	I <sub>inL</sub>	4 12	0.5 0.5		0.5 0.5			0.3 0.3		μAd
Output Voltage Logic 1	V <sub>OH</sub>	5 5 2	-1.060 -1.060 -1.060	-0.890 -0.890 -0.890	-0.960 -0.960 -0.960		-0.810 -0.810 -0.810	-0.890 -0.890 -0.890	-0.700 -0.700 -0.700	Vdd
		2	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700 -0.700	
Output Voltage Logic 0	V <sub>OL</sub>	5	-1.890	-1.675	-1.850		-1.650	-1.825	-1.615	Vdd
		5 2	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	7
		2	-1.890	-1.675	-1.850		-1.650	-1.825	-1.615	
Threshold Voltage Logic 1	$V_{OHA}$	5	-1.080		-0.980			-0.910		Vdd
		5 2	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		
		2	-1.080		-0.980			-0.910		
Threshold Voltage Logic 0	$V_{OLA}$	5		-1.655			-1.630		-1.595	Vdo
		5 2		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	
		2		-1.655		2	-1.630		-1.595	
Switching Times (50 $\Omega$ Load)							<b>&gt;</b>			ns
Propagation Delay	t <sub>4+2-</sub>	2	1.0	3.1	1.0	2.0	2.9	1.0	3.3	
		5	1.0	3.1	1.0	2.0	2.9	1.0	3.3	
	t <sub>4-5-</sub>	5	1.0	3.1	1.0	2.0	2.9	1.0	3.3	
Rise Time (20 to 80%)	t <sub>2+</sub> t <sub>5+</sub>	5	1.1 1.1	3.6 3.6	1.1 1.1	2.0 2.0	3.3 3.3	1.1 1.1	3.7 3.7	
,	_	2 5	1.1 1.1	3.6 3.6	1.1 1.1	2.0 2.0	3.3 3.3	1.1 1.1	3.7 3.7	
	$t_{4-2+}$ $t_{4+5+}$ $t_{4-5-}$ $t_{2+}$ $t_{5+}$	2 5 5 2 5	1.0 1.0 1.0 1.1 1.1	3.1 3.1 3.1 3.6 3.6 3.6	1.0 1.0 1.0 1.1 1.1	2.0 2.0 2.0 2.0 2.0 2.0	2.9 2.9 2.9 3.3 3.3	1.0 1.0 1.0 1.1 1.1	3.3 3.3 3.7 3.7 3.7	

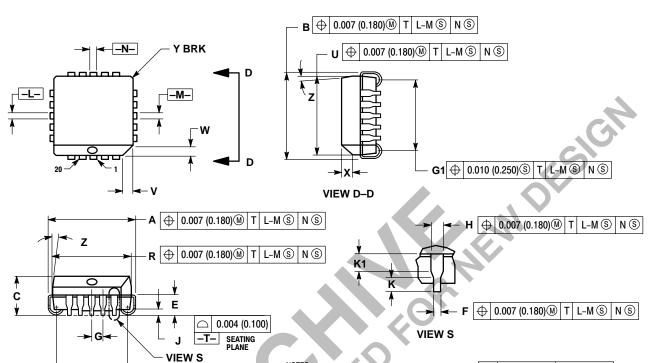
#### **ELECTRICAL CHARACTERISTICS** (continued)

					TEST VOI	TAGE VALU	JES (Volts)		
		@ Test Te	mperature	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>	
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
Pin			TEST V						
Characteristic		Symbol	Under Test	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>	(V <sub>CC</sub> ) Gnd
Power Supply Drain Current		ΙE	8					8	1, 16
Input Current		I <sub>inH</sub>	4 12	4 12				8 8	1, 16 1, 16
		I <sub>inL</sub>	4 12		4 12			8 8	1, 16 1, 16
Output Voltage	Logic 1	V <sub>OH</sub>	5 5 2 2	12 4				8 8 8 8	1, 16 1, 16 1, 16 1, 16
Output Voltage	Logic 0	V <sub>OL</sub>	5 5 2 2	12 4			la l	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Threshold Voltage	Logic 1	V <sub>OHA</sub>	5 5 2 2			12 4	12 4	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Threshold Voltage	Logic 0	V <sub>OLA</sub>	5 5 2 2	X		12 4	12 4	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Switching Times	(50Ω Load)					Pulse In	Pulse Out	-3.2 V	+2.0 V
Propagation Delay	(	t <sub>4+2-</sub> t <sub>4-2+</sub> t <sub>4+5+</sub> t <sub>4-5-</sub>	2 2 5 5			4 4 4 4	2 2 5 5	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Rise Time	(20 to 80%)	t <sub>2+</sub> t <sub>5+</sub>	2 5			4 4	2 5	8 8	1, 16 1, 16
Fall Time	(20 to 80%)	t <sub>2-</sub> t <sub>5-</sub>	2 5			4 4	2 5	8 8	1, 16 1, 16

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

#### PACKAGE DIMENSIONS

#### PLCC-20 **FN SUFFIX** PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



G1 

- NOTES:

  1. DATUMS -L.-, -M-, AND -N- DETERMINED
  WHERE TOP OF LEAD SHOULDER EXITS PLASTIC
  BODY AT MOLD PARTING LINE.
- BUDY AT MOLD PARTING LINE.

  2. DIMENSION 61, TRUE POSITION TO BE
  MEASURED AT DATUM -T-, SEATING PLANE.

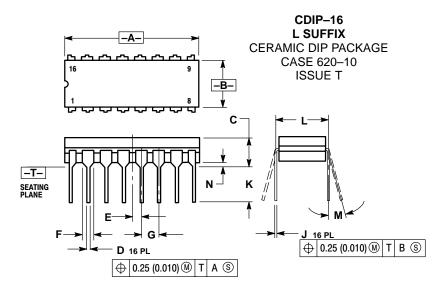
  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
  FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250)
  PER SIDE.

  DIMENSION AND TO EDAMOND FOR AND
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300).
  DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT
  INCLUDING ANY MISMATCH BETWEEN THE TOP
- INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

  DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.925).

	INC	HES	MILLIM	ETERS			
DIM	MIN	MAX	MIN	MAX			
Α	0.385	0.395	9.78	10.03			
В	0.385	0.395	9.78	10.03			
С	0.165	0.180	4.20	4.57			
Е	0.090	0.110	2.29	2.79			
F	0.013	0.019	0.33	0.48			
G	0.050	BSC	1.27	1.27 BSC			
Н	0.026	0.032	0.66	0.81			
J	0.020		0.51				
K	0.025		0.64				
R	0.350	0.356	8.89	9.04			
U	0.350	0.356	8.89	9.04			
٧	0.042	0.048	1.07	1.21			
W	0.042	0.048	1.07	1.21			
X	0.042	0.056	1.07	1.42			
Y		0.020	-	0.50			
Z	2°	10°	2°	10 °			
G1	0.310	0.330	7.88	8.38			
K1	0.040		1.02				

#### PACKAGE DIMENSIONS



#### NOTES:

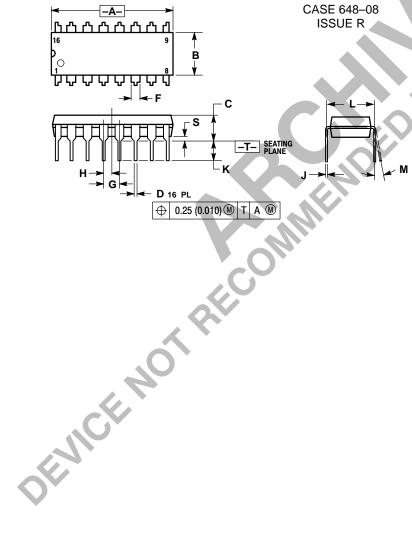
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
   DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

  DIMENSION F MAY NARROW TO 0.76 (0.030)
  WHERE THE LEAD ENTERS THE CERAMIC
  BODY.

	INC	HES	MILLIMETERS		
DIM	MIN MAX		MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
E	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62 BSC		
М	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

#### PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27	BSC	
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

# **Notes**



# **Notes**





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